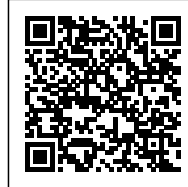




FEEDING EQUIPMENT DIE EJECT UNIT

SKU: S3-0097

69.000,00 € excl. VAT



Categories: [Feeding equipment](#), [Modules](#)

BESCHREIBUNG

The Die Eject Unit is used to load wafers and to release components from the wafer foil to make them available to the machine for further processing. The components fixed on the wafer foil are released with a Needle Vacuum System and thus separated.

The Die Eject Unit can handle wafer in sizes from 4" to 8".

The Die Eject Unit loads automatically wafers that are provided in a delivery system. The delivery system can be a laser-safe Single Wafer Loader or an automatic, laser-safe Single Wafer Changer. These are available separately.

MORE INFORMATION

Dimensions in mm (W x D x H)	363,5 x 594 x 151
Weight in kg	16,7
Max. wafer size in inch / mm	8 / 200
Voltage in V	24
Max. current in A	5
Communication interface	Ethernet , UNICAN

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